PCN Number:	20201112000.1	**PCN Date:**	Nov 19, 2020
Title:	Qualification of an additional Substrate Manufacturing Subcontractor for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Feb 19, 2021	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

TI is qualifying an additional substrate manufacturing subcontractor (ACCESS) for the devices in the product affected section shown below. Assembly site origin (ASO) will remain unchanged. Construction differences are as follows:

	Current (ATNS)	**New (ACCESS)**
Substrate Material	R1551W	**6785GTK**
Solder mask	XV501T	**SR7300G**
Adhesive	AD222	**N/A**
Cavity Filler	N/A	**ABF GX-T31**
L1/L2 metal	23um Cu	**15um Cu**
Surface Finish	OSP	**OSP**

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp

Changes to product identification resulting from this PCN:

N/A

Product Affected:

TPS82740ASIPR	TPS82740ASIPT	TPS82740BSIPR	TPS82740BSIPT

Qualification Report

Approve Date 16-Oct-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS82740ASIPR	QBS Process Reference: TPS82130PSIL
HAST	Biased HAST, 110C/85%RH	264 Hours	1/77/0	2/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	QBS	3/231/0
SD	Pb Free Surface Mount Solderability	4 hour @ 155C aging	1/22/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	3/239/0
UHAST	Unbiased HAST 110C/85%RH	264 Hours	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 hours	1/77/0	-

- QBS: Qual By Similarity
- Qual Device TPS82740xSIPR devices are qualified at LEVEL2-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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